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TDTP2500P100: 2.5kW Bridgeless Totem-pole PFC Evaluation Board

Overview

This user guide describes the TDTP2500P100_Ov1 2.5kW bridgeless totem-pole power factor correction (PFC) evaluation board. Very high efficiency single-phase AC-DC conversion is achieved with the TPH3212PS, a diode-free Gallium Nitride (GaN) FET bridge with low reverse-recovery charge. Using GaN FETs in the fast-switching leg of the circuit and low-resistance MOSFETs in the slow-switching leg of the circuit results in improved performance and efficiency. For more information and complete design files, please visit transphormusa.com/tp25kit. The TDTP2500P100_Ov1-KIT is for evaluation purposes only.

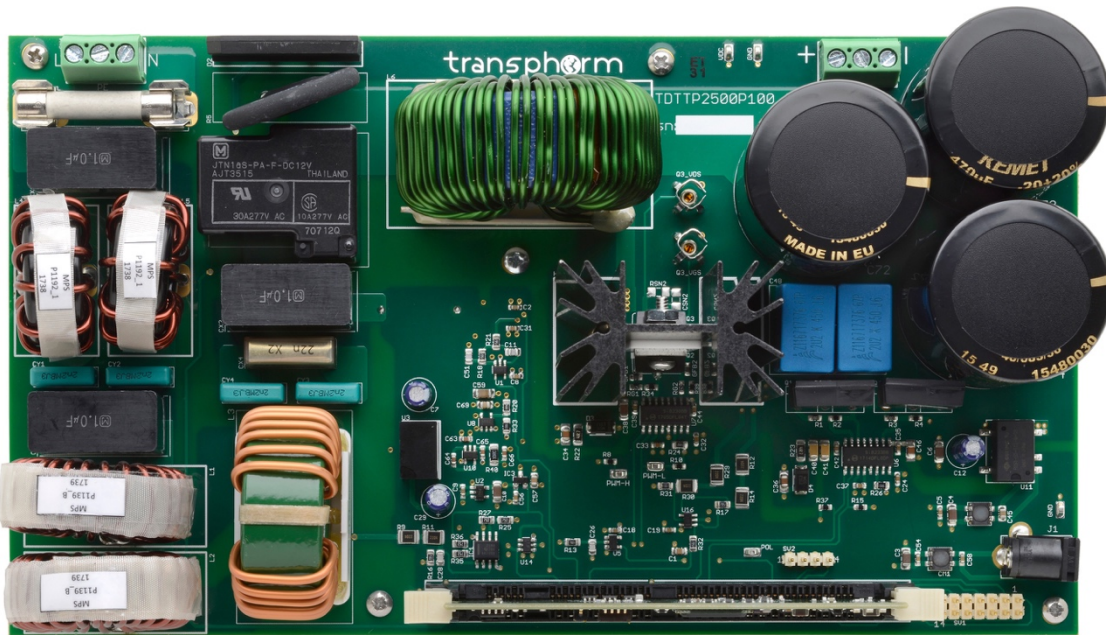


Figure 1. TDTP2500P100_Ov1 2.5kW totem-pole PFC evaluation board

Warning



This evaluation board is intended to demonstrate GaN FET technology and is for demonstration purposes only and no guarantees are made for standards compliance.

There are areas of this evaluation board that have exposed access to hazardous high voltage levels. Exercise caution to avoid contact with those voltages. Also note that the evaluation board may retain high voltage temporarily after input power has been removed. Exercise caution when handling.

When testing converters on an evaluation board, ensure adequate cooling. Apply cooling air with a fan blowing across the converter or across a heatsink attached to the converter. Monitor the converter temperature to ensure it does not exceed the maximum rated per the datasheet specification.

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The TDTP2500P100-KIT includes:

- TDTP2500P100 totem-pole PFC assembly
- Texas Instruments F28335 control card
- 12V_{DC} auxiliary power adaptor

Complete design files and support documentation can be found online at transphormusa.com/tp25kit.

TDTP2500P100 input/output specifications

- Input voltage: 85V_{AC} to 265V_{AC}, 47Hz to 63Hz
- Input current: 18A_{RMS}; 1250W at 115V_{AC}, 2500W at 230V_{AC}
- 10% overload short time: 11A_{RMS}; 1250W at 115V_{AC}, 2500W at 230V_{AC}
- Ambient temperature: <50°C
- Output voltage: 390V_{DC} ± 5V_{DC}
- PWM frequency: 100kHz
- Auxiliary supply: 12V_{DC} for bias voltage
- Power dissipation in the GaN FET: Limited by the maximum junction temperature; refer to the [TPH3212PS](#) datasheet

Figure 2 shows the input and output connections. To reduce EMI noise, adding a ferrite core at both the input and output is recommended.

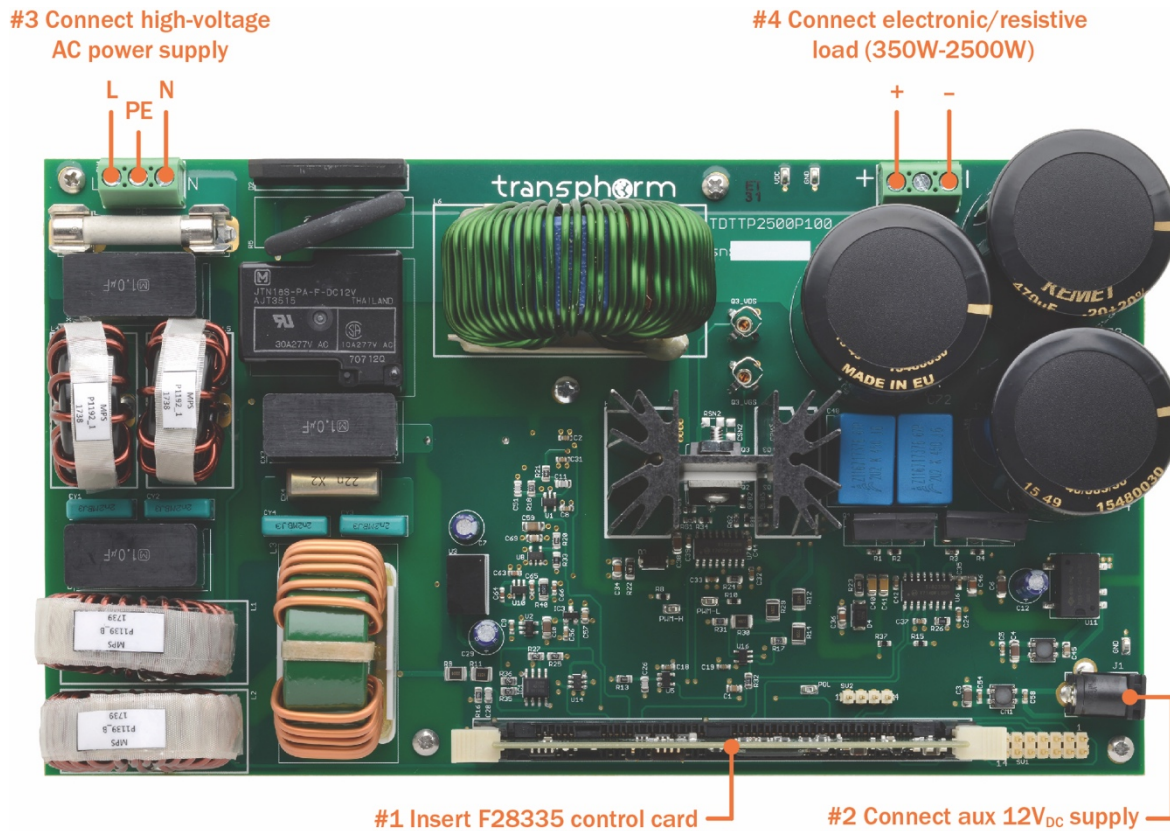


Figure 2. Input and output cable connections

Circuit description

The bridgeless totem-pole PFC topology is shown in Figure 3. Two GaN FETs and two low-resistance silicon (Si) MOSFETs are used to eliminate diode drops and improve efficiency. Further information and discussion on the performance and the characteristics of the bridgeless PFC circuit is provided in [1].

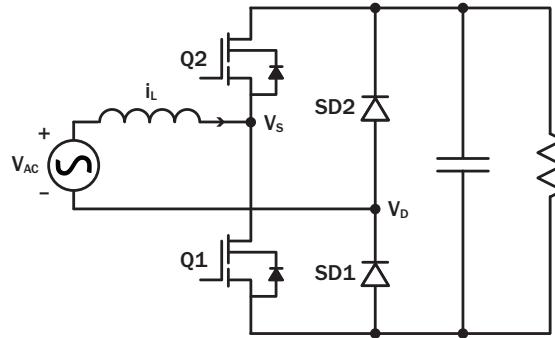


Figure 3. Bridgeless totem-pole PFC boost converter based on low-resistance MOSFETs for line rectification

Figure 4(a) is a simplified schematic of a totem-pole PFC in continuous conduction mode (CCM) mode, focused on minimizing conduction losses. It comprises two fast-switching GaN FETs (Q1 and Q2) operating at a high pulse-width-modulation (PWM) frequency and two very low-resistance MOSFETs (S1 and S2) operating at a much slower line frequency (50Hz/60Hz). The primary current path includes one fast switch and one slow switch only, with no diode drop. The function of S1 and S2 is that of a synchronized rectifier as illustrated in Figures 4(b) and 4(c). During the positive AC cycle, S1 is on and S2 is off, forcing the AC neutral line tied to the negative terminal to the DC output. The opposite applies for the negative cycle.

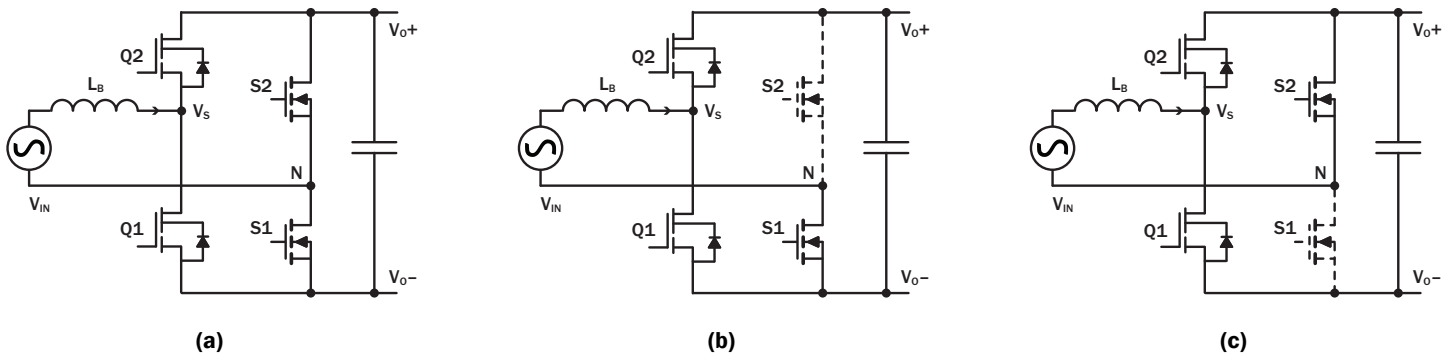


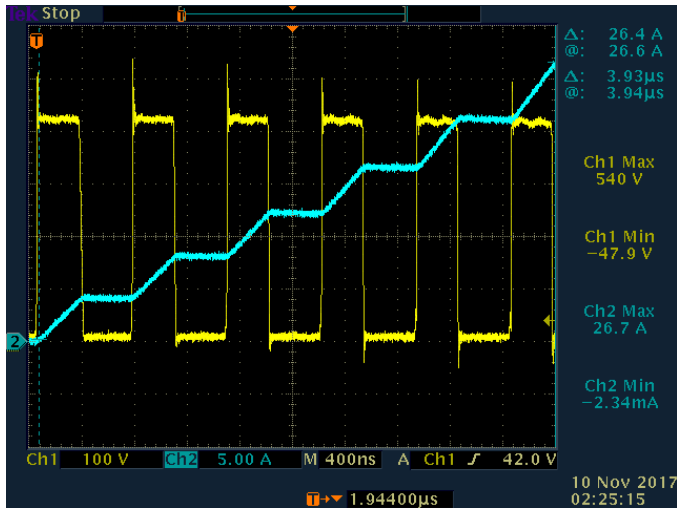
Figure 4. Totem-pole PFC with GaN FETs (a) simplified schematic, (b) during positive AC cycle and (c) during negative AC cycle

In either AC polarity, the two GaN FETs form a synchronized boost converter with one transistor acting as a master switch to allow energy intake by the boost inductor (LB), and another transistor as a slave switch to release energy to the DC output. The roles of the two GaN devices interchange when the polarity of the AC input changes; therefore, each transistor must be able to perform both master and slave functions. To avoid shoot-through a dead time is built in between two switching events, during which both transistors are momentarily off. To allow CCM operation, the body diode of the slave transistor must function as a flyback diode for the inductor current to flow during dead time. The diode current; however, must quickly reduce to zero and transition to the reverse blocking state once the master switch turns on.

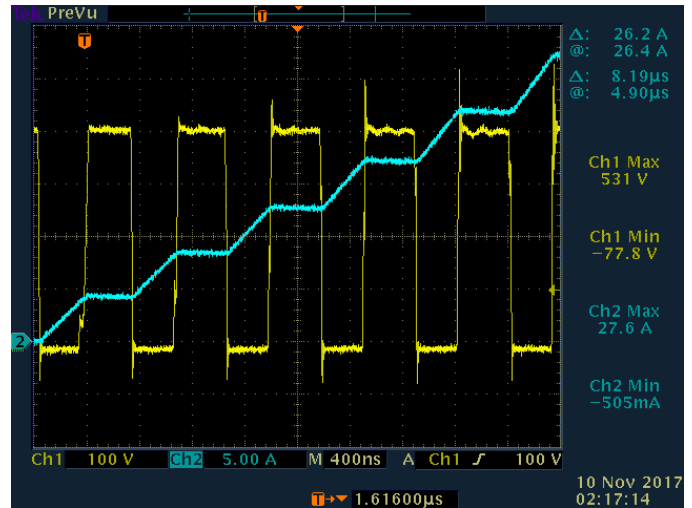
This is the critical process for a totem-pole PFC which, with the high Q_{RR} of the body diode of high-voltage Si MOSFETs, results in abnormal spikes, instability, and associated high switching losses. The low Q_{RR} of the GaN switches allows designers to overcome this barrier.

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As seen in Figure 5, inductive tests at 400V bus show healthy voltage waveforms up to inductor current exceeding 27A using either a high-side (Figure 5(a)) or low-side (Figure 5(b)) GaN transistor as a master switch. With a design goal of 2.5kW output power in CCM mode at 230V_{AC} input, the required inductor current is 12A. This test confirms a successful totem-pole power block with enough current overhead.



(a) High side



(b) Low side

Figure 5. Waveforms of two hard-switched GaN FETs when setting (a) high-side as a master and (b) low-side as a master

One issue inherent in the bridgeless totem-pole PFC is the operation mode transition at AC voltage zero-crossing. For instance, when the circuit operation mode changes from positive half-line to negative half-line at the zero-crossing, the duty ratio of the high-side GaN switch changes abruptly from almost 100% to 0% and the duty ratio of low-side GaN switch changes from 0% to 100%. Due to the slow reverse recovery of diodes (or body diode of a MOSFET), the voltage V_D cannot jump from ground to V_{DC} instantly; a current spike will be induced. To avoid the problem, a soft-start at every zero-crossing is implemented to gently reverse duty ratio (a soft-start time of a few switching cycles is enough). The TDTP2500P100 evaluation board is designed to run in CCM and the larger inductance alleviates the current spike issue at zero-crossing.

Dead time control

The required form of the gate-drive signals is shown in Figure 5. The times marked A are the dead times when neither transistor is driven on. The dead time must be greater than zero to avoid shoot-through currents. The Si8230 gate drive chip ensures a minimum dead time based on the value of resistor R24, connected to the DT input. The dead time in ns is equal to the resistance in k Ω x 10, so the default value of 12k corresponds to 120ns. This will add to any dead time already present in the input signals. The on-board pulse generator circuit; for example, creates dead times of about 60ns (see Figure 6). The resulting dead time at the gate pins of Q1 and Q2 is about 100ns. Either shorting or removing R24 will reduce the dead time to 60ns.

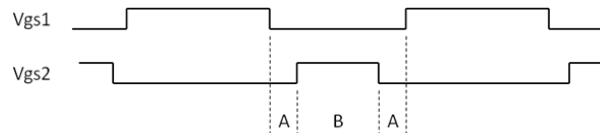


Figure 6. Non-overlapping gate pulses

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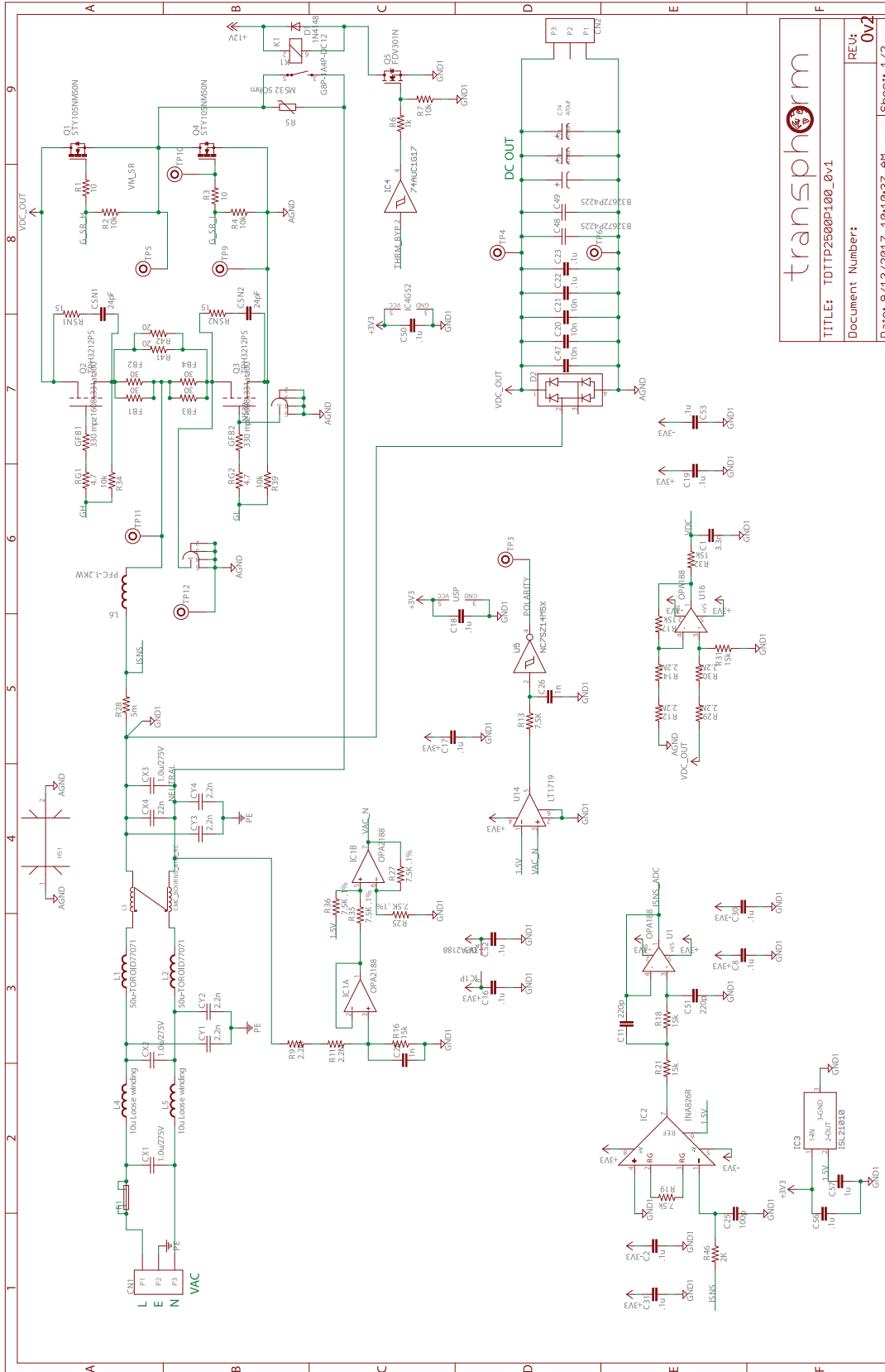
While a typical Si MOSFET has a maximum dV/dt rating of 50V/ns, the TPH3212PS GaN FET will switch at dV/dt of 100V/ns or higher to achieve the lowest possible switching loss. At this level of operation, even the layout becomes a significant contributor to performance. As shown in Figure 8, the recommended layout keeps a minimum gate drive loop and keeps the traces between the switching nodes very short—with the shortest practical return trace to the power bus and ground. The power ground plane provides a large cross-sectional area to achieve an even ground potential throughout the circuit. The layout carefully separates the power ground and the IC (small signal) ground, only joining them at the source pin of the FET to avoid any possible ground loop.

Note that the Transphorm GaN FETs in TO-220 packages have pinout configuration of G-S-D, instead of the traditional G-D-S of a MOSFET. The G-S-D configuration is designed with thorough consideration to minimize the gate source driving loop, reducing parasitic inductance and to separate the driving loop (gate source) and power loop (drain source) to minimize noise. All PCB layers of the TDTP2500P100 design are shown Figure 8(a-c) and available in the [design files](#).

Design details

A detailed circuit schematic is shown in Figures 7 and 8, the PCB layers in Figure 9, and the parts list in Table 1 (also included in the [design files](#)).

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Figure 7. Detailed circuit schematic (1 of 2)

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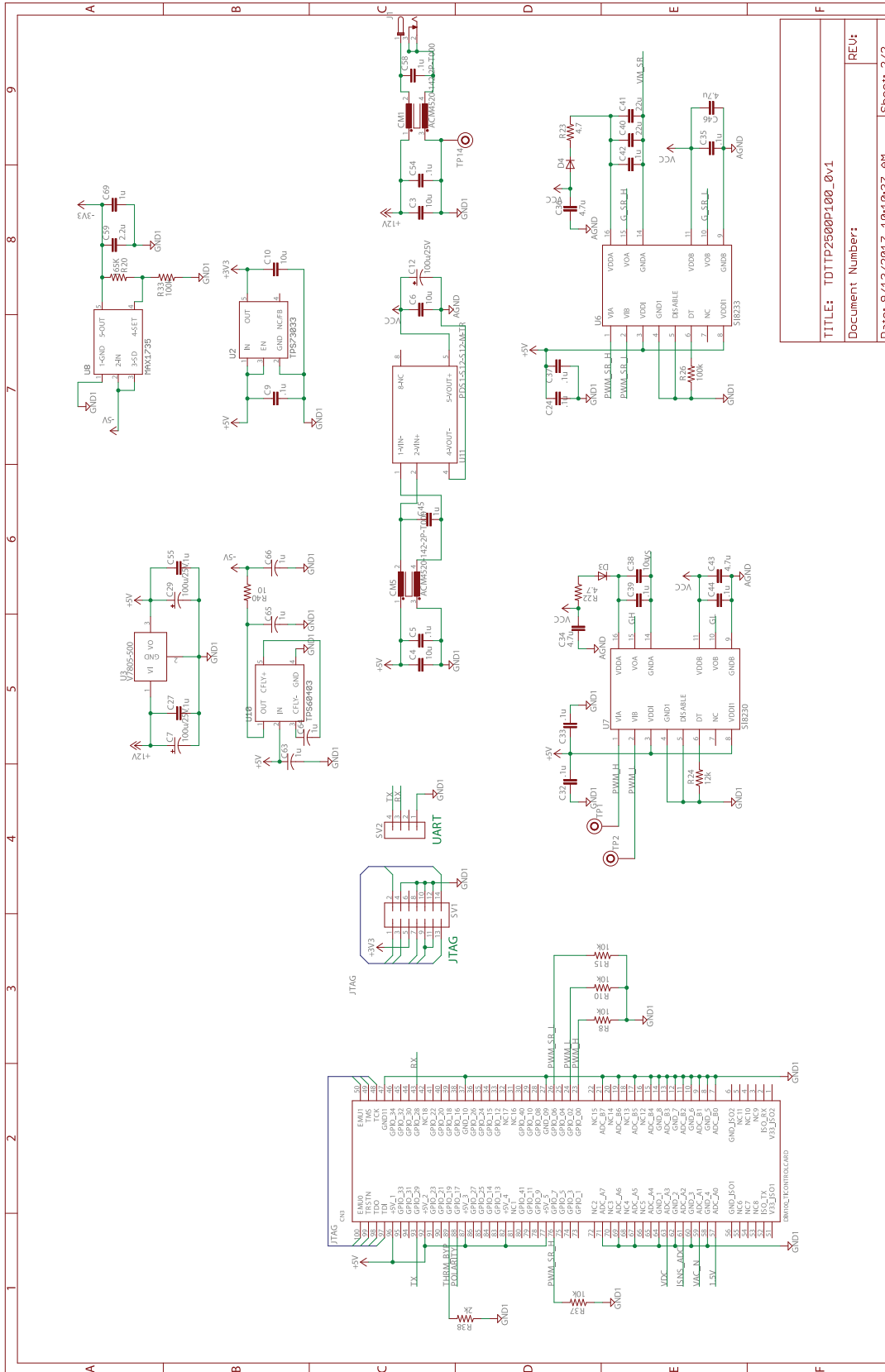


Figure 8. Detailed circuit schematic (2 of 2)

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Table 1. TDTP2500P100 evaluation board bill of materials (BOM)

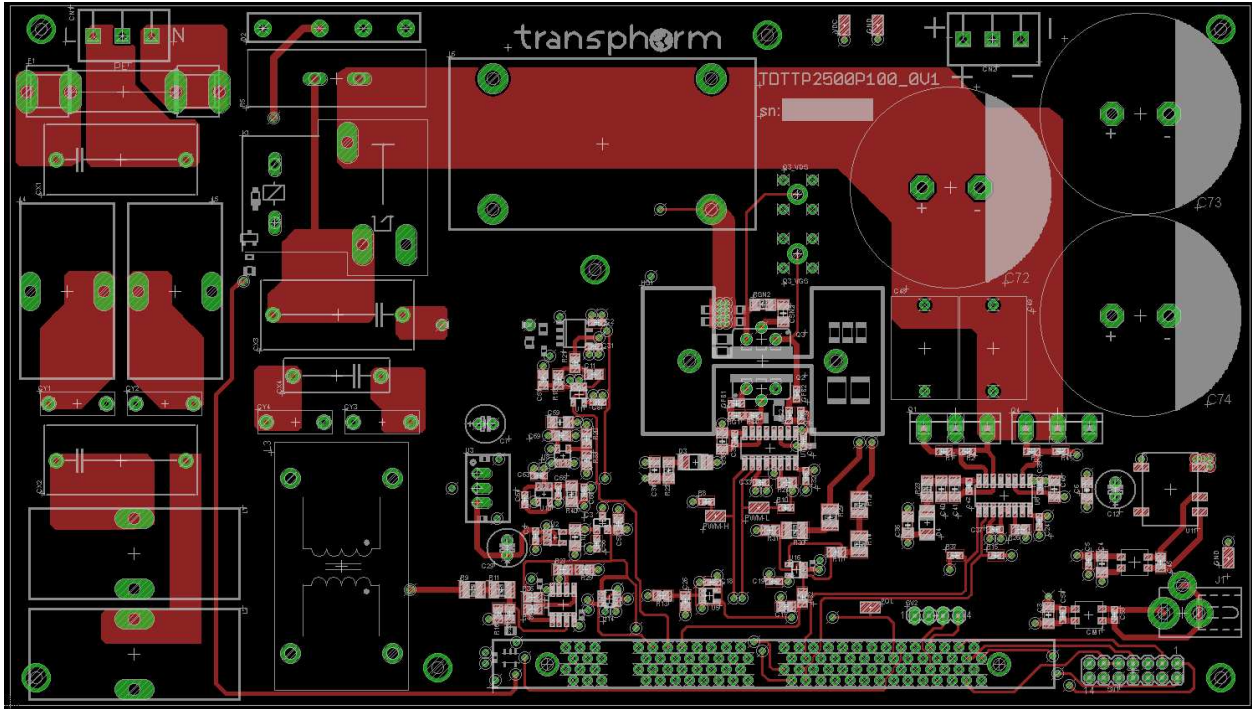
Designator	Qty	Value	Descriptor/Package	Manufacturer Part Number	Manufacturer
HS1	1		529802B02500G	530002B02500G	Aavid Thermalloy
D3, D4	2		DIODE-DO-214AC	ES1J	Micro Commercial
CN1, CN2	2		FCI_20020316-3P	20020316-H031B01LF	FCI
D2	1		GBJ2506	GBJ2506-BP	Micro Commercial
SV2	1		MA04-1	961104-6404-AR	3M
SV1	1		MA07-2	67996-114HLF	FCI
J1	1		PJ-002AH	PJ-002AH	CUI
F1	1		SH32	01020078H	Littelfuse
TP7, TP8	2		TEKTRONIX-PCB	131-4353-00	Tektronix
TP1, TP2, TP3, TP4, TP5, TP6, TP9, TP10, TP11, TP12, TP14	11		TESTPOINT-KEYSTONE5015	5015	Keystone
C2, C5, C8, C9, C16, C17, C18, C19, C24, C27, C30, C31, C32, C33, C35, C37, C39, C42, C44, C50, C52, C53, C54, C55, C56, C58	26	0.1µF	C-EUC0603	CC0603KRX7R8BB104	Yageo
C22, C23	2	0.1µF	C-EUC1812	C1812V104KDRACTU	Kemet
CX1, CX2, CX3	3	1µF/275V	ECQ-U2A474ML1.0U	ECQ-U2A105ML	Panasonic
R1, R3	2	10Ω	R-US_R0603	RNCP0603FTD10R0	Stackpole
R40	1	10Ω	R-US_R1206	ERJ-8ENF10ROV	Panasonic
R26, R33	2	100kΩ	R-US_R0805	RJ-6ENF1003V	Panasonic
C25	1	100pF	C-EUC0603	06035A101FAT2A	AVX Corporation
C7, C12, C29	3	100µF/25V	CPOL-USE2.5-7	ESK107M025AC3AA	Kemet
R2, R4, R7, R8, R10, R15, R34, R37, R39	9	10kΩ	R-US_R0603	ESR03EZPJ103	ROHM Semiconductor
C20, C21, C47	3	10nF	C-EUC1206	C3216COG2J822J160AA	TDK
C3, C4, C6, C10, C38	5	10µF	C-EUC1206	CL31A106KAHNNNE	Samsung Electro-Mechanics
L4, L5	2	10µF loose winding	DM-TOROID	P1192_1	MPS Industries
R24	1	12kΩ	R-US_R0805	RC0805FR-0712KL	Yageo
RSN1, RSN2	2	15Ω	R-US_R1206	RNCP1206FTD15R0	Stackpole
R16, R17, R18, R21, R31, R32	6	15kΩ	R-US_R0805	05FR-0715KL	Yageo
R20	1	165kΩ	R-US_R0805	ERJ-6ENF1653V	Panasonic
D1	1		DIODE-SOD123	1N4148W-E3-18	Vishay
R6	1	1kΩ	R-US_R0805	RC0805JR-071KL	Yageo
C26, C28	2	1nF	C-EUC0805	CC0805KRX7R9BB102	Yageo
C45, C57, C69	3	1µF	C-EUC0805	CC0805ZRY5V8BB105	Yageo
C63, C64, C65, C66	4	1µF	C-USC0603	TMK107B7105KA-T	Taiyo Yuden
R9, R11, R12, R14, R29, R30	6	2.2MΩ	R-US_R1210	KTR25JZPF2204	ROHM Semiconductor
CY1, CY2, CY3, CY4	4	2.2nF	PHE850YCAP	PHE850EA4220MA01R17	Kemet
C59	1	2.2µF	C-EUC1206	CL31B225KAHNNNE	Samsung Electro-Mechanics
R41, R42	2	20Ω	R-US_R1206	RNCP1206FTD20R0	Stackpole
C11, C51	2	220pF	C-EUC0805	CC0805KRX7R9BB221	Yageo
CX4	1	22nF	ECQ-U2A474ML22N	PME271M522MR30	Kemet
C40, C41	2	22µF	C-EUC1206	CL31A226KAHNNNE	Samsung Electro-Mechanics
CSN1, CSN2	2	47pF	C-EUC1206	CL31C470JIFNFNE	Samsung Electro-Mechanics
R38, R46	2	2kΩ	R-US_R0805	ERJ-6ENF2001V	Panasonic
C1	1	3.3nF	C-EUC0805	C0805C332K5RACTU	Kemet
FB1, FB2, FB3, FB4	4	30Ω	R-US_R0805	BLM21SN300SH1D	Murata
GFB1, GFB2	2	330Ω	R-US_R0603	MPZ1608S331ATA00	TDK
RG1, RG2	2	4.7Ω	R-US_R0603	ESR03EZPJ4R7	ROHM Semiconductor
R22, R23	2	4.7Ω	R-US_R1206	CRM1206-JW-4R7ELF	Bourns

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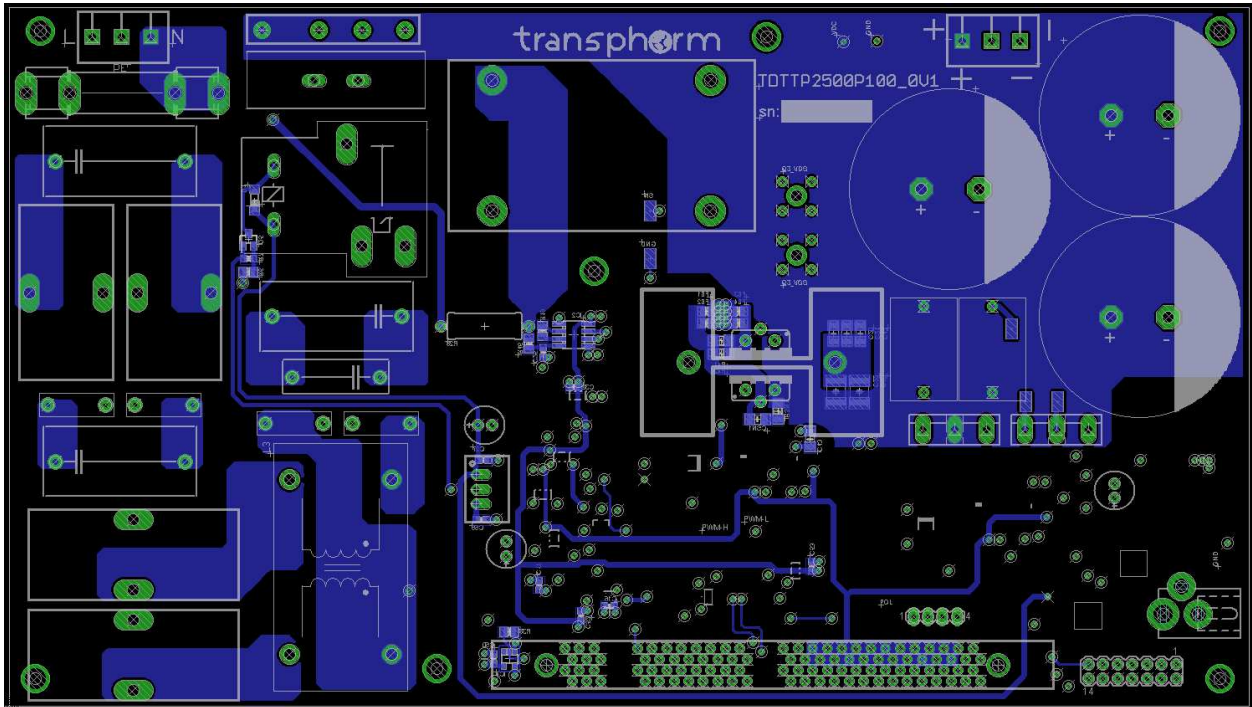
Designator	Qty	Value	Descriptor/Package	Manufacturer Part Number	Manufacturer
C34, C36, C43, C46	4	4.7 μ F	C-EUC1206	C0805C475K4PACTU	Kemet
C72, C73, C74	3	470 μ F	ELE_CAP_D35MM_P10MM	ALC10A471DF450	Kemet
L1, L2	2		DM-TOROID77071	P1139 rev A.	MPS Industries
R28	1	5m Ω	R-US_0613/15	12FR005E	Ohmite
R19, R13	2	7.5k Ω 0.1%	R-US_R0805	RC0805FR-077K5L	Yageo
R25, R27, R35, R36	4	7.5k Ω 0.1%	R-US_R0805	ERA-6AEB752V	Panasonic
IC4	1		74AUC1G17DBV	SN74LVC1G17DBVR	Texas Instruments
CM1, CM5	2		ACM4520	ACM4520-142-2P-T000	TDK
C48, C49	2		B32672P4225	B32672P4225K	Epcos (TDK)
L3	1		CMC_BOURNS_8119_RC	8121-RC	Bourns
CN3	1		DIMM socket	5390213-1	TE Connectivity
Q5	1		BSS138-7-F	FDV301N	Fairchild/ON Semiconductor
K1	1		JTN1AS-PA-F-DC12V	JTN1AS-PA-F-DC12V	Omron Electronics
IC2	1		INA826R	INA826AID	Texas Instruments
IC3	1		ISL21010	ISL21010CFH315Z-TK	Intersil
U14	1		LT1719	LT1719CS6#TRMPBF	Linear Technology
U8	1		MAX1735	MAX1735EUK50+T	Maxim Integrated
R5	1	10 Ω	THERMISTOR-AMETHERM	SL32 10015	Ametherm
U5	1		NC7SZ14M5X	NC7SZ14M5X	Fairchild/ON Semiconductor
U1, U16	2		AD8031RJ	OPA188AIDBVT	Texas Instruments
IC1	1		AD826R	OPA2188AIDR	Texas Instruments
U11	1		PDS1-S5-S12-M-TR	PDS1-S5-S12-M-TR	CUI
L6	1		P1941_A	P1941_A	MPS Industries
U7	1		SI8230	SI8230BB-D-IS1	Silicon Labs
U6	1		SI8233	SI8233BB-D-IS1	Silicon Labs
Q1, Q4	2		STY105NM50N	STY105NM50N	STMicroelectronics
Q2, Q3	2		TPH3212PS	TPH3212PS	Transphorm
U10	1		TPS60403	TPS60403DBVR	Texas Instruments
U2	1		TPS73033	TPS73033DBVR	Texas Instruments
U3	1		V7805-500	7805-500	CUI
	7		Stand off (nylon 1/2)	1902C	Keystone
	7		Machine screw (ss 1/2)	9902	Keystone
	1		Thermal pad for Q3	4169G	Aavid Thermalloy
	1		Screw for FETs HS	9902	Keystone
	2		Washer shoulder to be placed between screw and FET assembly	3049	Keystone
	1		Nut for FETs to HS	9600	Keystone
	1		Control card	TMDSCNCD28335	Texas Instruments
	1		12Vdc aux supply	SW110-12-N-P5	CUI

For the TDTP2500P100 evaluation board, the PFC circuit has been implemented on a 4-layer PCB. The GaN FET half-bridge is built with Transphorm's TPH3212PS (72m Ω) GaN FET. The slow Si switches are STY105NM50N (22m Ω) superjunction MOSFETs. The inductor is made of a High Flux core with an inductance of 480 μ H and a DC resistance of 25m Ω and designed to operate at 100kHz. A simple 0.5A rated high/low side driver IC (Si8230) with 0/12V as on/off states directly drives each GaN FET. A 150MHz DSP (TMS320F28335) handles the control algorithm. The voltage and current loop controls are similar to a conventional boost PFC converter. The feedback signals are DC output voltage (V_o), AC input potentials (V_{ACP} and V_{ACN}) and inductor current (IL). The input voltage polarity and RMS value are determined from V_{ACP} and V_{ACN} . The outer voltage loop output multiplied by $|V_{AC}|$ gives a sinusoidal current reference. The current loop gives the proper duty ratio for the boost circuit. The polarity determines how PWM signal is distributed to drive Q1 and Q2. A soft-start sequence with a duty ratio ramp is employed for a short period at each AC zero-crossing for better stability.

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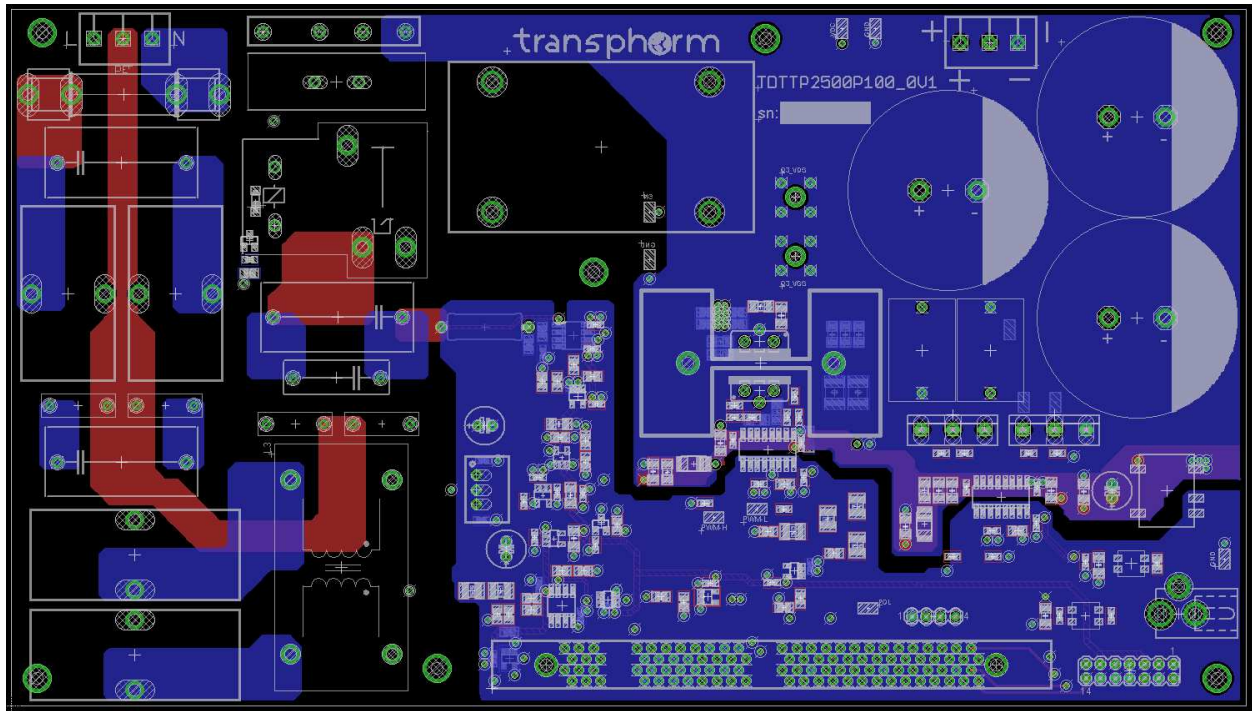


(a) PCB top layer



(b) PCB bottom layer

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(c) PCB inner layer 2 (ground plane) + inner layer 3 (power plane)

Figure 9. PCB layers

Using the board

The TDTP2500P100 board can be used for evaluating Transphorm GaN FETs in a bridgeless totem-pole PFC circuit and is building block but not a complete circuit.

Powering on the board

1. Insert the control card
 - LED1 ON indicates DSP power is on
 - LED2 BLINKING indicates the DSP is running
 - LED3 ON indicates the DSP has stopped running due to fault protection (over voltage or current)
2. Connect an electronic/resistive load to the corresponding marking (CN2). The requirements for the resistive load are
 - At 115V_{AC} input: 350W to $\leq 1250W$
 - At 230V_{AC} input: 350W to $\leq 2500W$
3. Connect the 12V_{DC} auxiliary supply (included) to the evaluation board
4. With high-voltage power off, connect the high-voltage AC power input to the corresponding marking (CN1) on the PCB; N and L (PE: potential ground)
5. Turn on the AC power input (85V_{AC} to 265V_{AC}, 50Hz to 60Hz); minimum power load for turn-on sequence is 350W
6. Monitor CN2 output voltage with V_{DC} meter to verify that 390V $\pm 5V$ is generated
7. Electronic/resistive load can be increased while AC supply is on and board is functional

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Powering off the board

1. Switch off the high-voltage AC power input
2. Power off DC bias

Operational waveforms

Figure 10 shows the converter start-up procedure: DC input current (CH1), DC bus voltage waveform (CH2), and voltage waveform of the fast leg switching node (CH3). For the start up, there are three phases to charge the DC bus to a reference voltage.

1. In the beginning the relay K1 is open and DC bus capacitors are charged by input voltage through NTC and diode bridge
2. When the V_{DC} is over 100V, K1 is closed to bypass the NTC and the V_{DC} increases to the peak of the input voltage
3. After 100ms, the leg of the GaN FET is engaged in voltage closed-loop control and the DC bus voltage reference slowly increases to the rated voltage 385V

The NTC and diode bridge are applied in this circuit to avoid high inrush current flow through the GaN FETs.

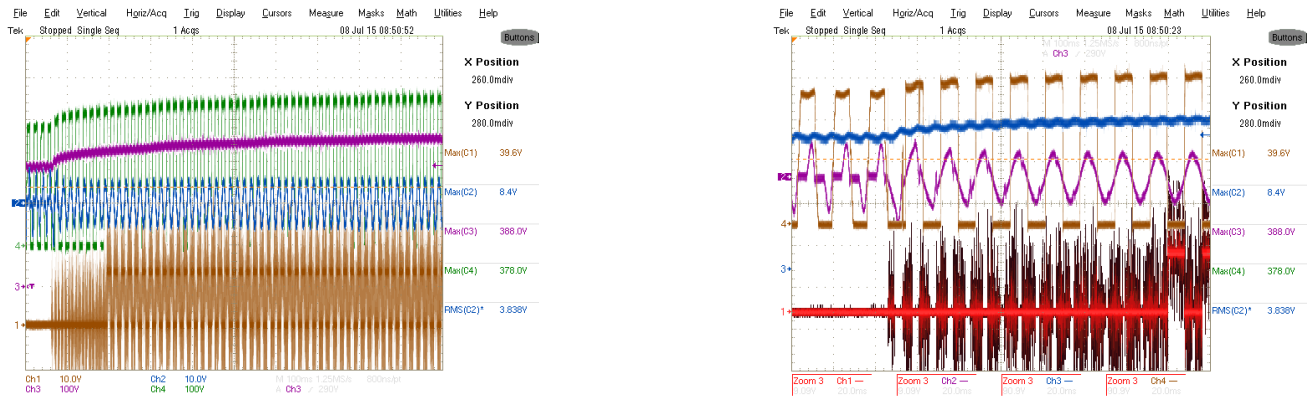


Figure 10. Start-up of the bridgeless totem-pole PFC
CH1: V_G , CH2: i_L , CH3: V_o , CH4: V_D

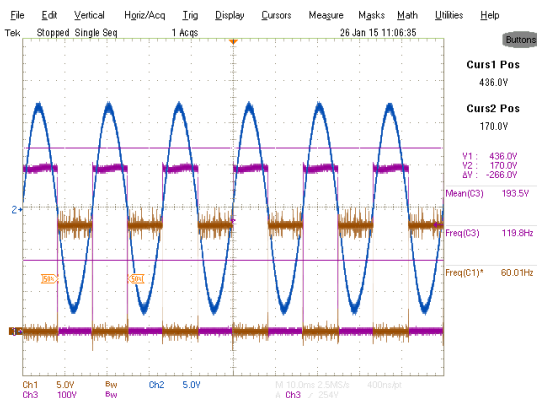


Figure 11. Active switch version of the bridgeless totem-pole PFC at low line, full load
CH1: PWM gate signal for S_{D2} , CH2: i_L waveform (10A/div),
CH3: V_D waveform (100V/div), CH4: AC input polarity signal

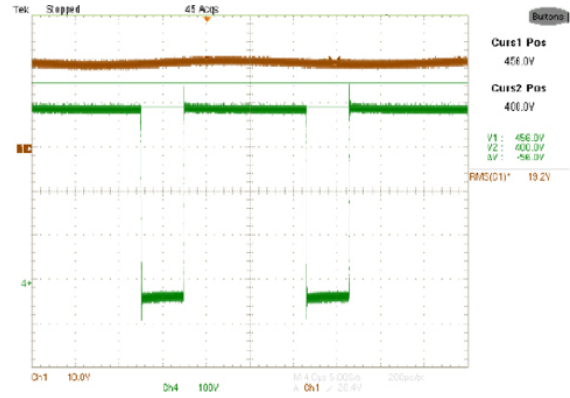


Figure 12. Waveform of V_{DS} of Q2 at $i_L=20A$
CH1: $I_{IN}=10A/div$, CH2: $V_{DS}=100V/div$

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Figure 13 shows the transition between two half-cycles. In Figure 13(a) the AC line enters the negative half and soft-start gradually increases voltage V_D from 0V to 385V, and in Figure 13(b), V_D decreases from 385V to 0V.

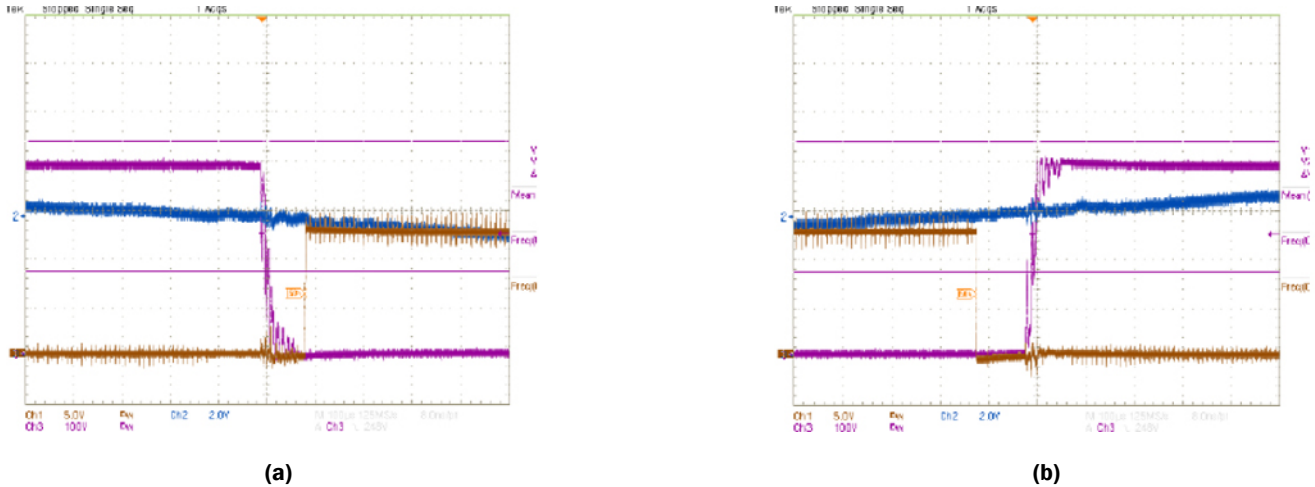


Figure 13. Zero-crossing transitional waveforms (a) from negative to positive half-cycle and (b) from positive to negative half-cycle
CH1: PW<gate signal for S_{D2} , CH2: I_L , CH3: V_D

Probing

As shown in Figure 14, on the evaluation board there are two probing sockets for measuring V_{GS} and V_{DS} of low side GaN FET and MOSFET.



Probing tips: Low side GaN FET V_{GS} and V_{DS}



Passive voltage probes

Figure 14. V_{GS} and V_{DS} of low side GaN FET measurement socket tips and current measurement position

Efficiency sweep and EMI

For the efficiency measurement, the input/output voltage and current will be measured for the input/output power calculation with a power analyzer. Efficiency has been measured at 120V_{AC} or 230V_{AC} input and 390V_{DC} \pm 5V output using the WT1800 precision power analyzer from Yokogawa. The efficiency and power loss results for the TDTP2500P100 are shown in Figure 15. The extremely high efficiency of 98.9% at 230V_{AC} input, and 97.5% at 115V_{AC} input is the highest among PFC designs with similar PWM frequency, enabling customers to reach peak system efficiency that meets or exceeds the 80 PLUS standard.

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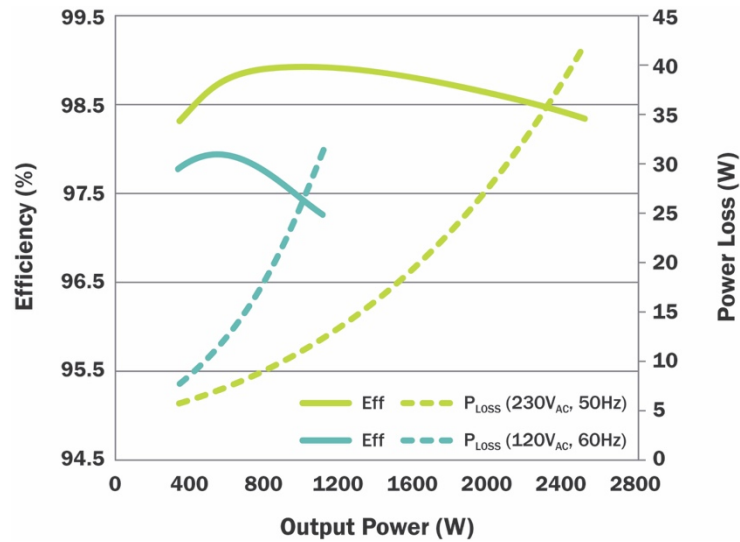


Figure 15. TDTP2500P100 efficiency results

Conducted emissions have also been measured for this board using an LIN-115A LISN by Com-Power. The results compared to EN55022A limits are shown in Figure 16. **Note that the EMI test was done by using the lab-use power supply for an auxiliary 12V source. Do not use wall AC-DC adaptor for the EMI test.**

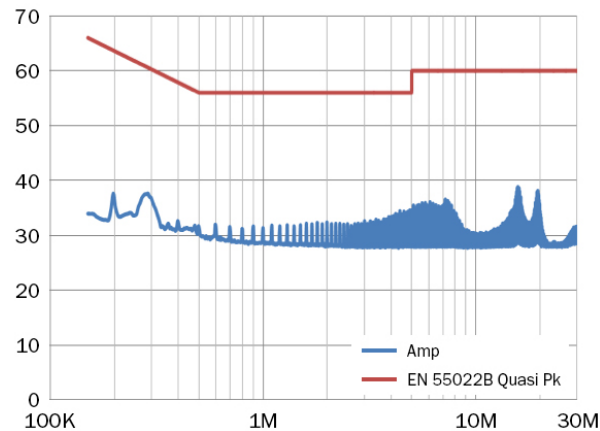


Figure 16. Conducted emissions @ 115V, 680W

Maximum load limit

The TDTP2500P100 evaluation board can run overload in a short time. The rated input current for $230V_{AC}$ input is 11A and the 10% overload current can be 12A. The input over-current protection (OCP) will be triggered when the current is over 12A.

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Warnings

The TDTP2500P100 is for evaluation purposes only and is not intended to be a finished product and does not include all protection features found in commercial power supplies. Additional warnings to keep in mind:

1. An isolated AC source should be used as input. An isolated lab bench-grade power supply or the included AUX DC supply should also be used for the 12V DC power supply. Float the oscilloscope by using an isolated oscilloscope or by disabling the PE (Protective Earth) pin in the power plug. Float the current probe power supply (if any) by disabling the PE pin in the power plug.
2. Use a resistive load only. The totem-pole PFC kit can work at zero load with burst mode and the output voltage will be swinging between 375V and 385V during burst mode.
3. The evaluation board is not fully-tested at large load steps. **DO NOT** apply a very large step in the load (>1000W) when it is running.
4. **DO NOT** manually probe the waveforms when the board is running. Set up probing before powering up the demo board.
5. The auxiliary V_{DC} supply must be 12V. The evaluation board will not work under 10V or over 15V V_{DC} , for example.
6. **DO NOT** touch any part of the evaluation board when it is running.
7. When plugging the control cards into the socket, make sure the control cards are fully pushed down with a clicking sound.
8. If the evaluation circuit goes into protection mode it will work as a diode bridge by shutting down all PWM functions. Recycle the bias power supply to reset the DSP and exit protection mode.
9. **DO NOT** use a passive probe to measure control circuit signals and power circuit signals at the same time. GND1 and AGND are not the same ground.
10. To get clean V_{GS} of the low side GaN FET, it is not recommended to measure the V_{DS} at the same time.
11. It is not recommended to use a passive voltage probe for V_{DS} and V_{GS} measurements while simultaneously using a differential voltage probe for V_{IN} measurements, unless the differential probe has very good dV/dt immunity.

References

- [1] Z. Liang, U. Mishra and Y. Wu, "True Bridge-less Totem-pole PFC based on GaN FETs," in *PCIM*, Europe, pp. 1017-1022, May 2013.